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(12) **United States Design Patent**  
**Podubni**

(10) **Patent No.: US D833,994 S**

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(54) **MODULAR CIRCUIT BOARD**

(71) Applicant: **Tiny PCB, Inc.**, San Jose, CA (US)  
(72) Inventor: **Edward Podubni**, San Jose, CA (US)  
(73) Assignee: **TinyPCB, Inc.**  
(\*\*) Term: **15 Years**

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(52) **U.S. Cl.**  
USPC ..... **D13/182**

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361/761, 807; 439/55, 65, 68, 76.1, 92,  
439/93, 95  
CPC ..... H05K 3/00; H05K 3/30; H05K 3/301;  
H05K 3/303; H05K 3/34; H05K 3/3405;  
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H05K 7/1422; H05K 7/00; H05K 1/18;  
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H05K 1/183; H05K 1/184; H05K 1/189;  
H05K 1/00

See application file for complete search history.

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*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Cooley LLP

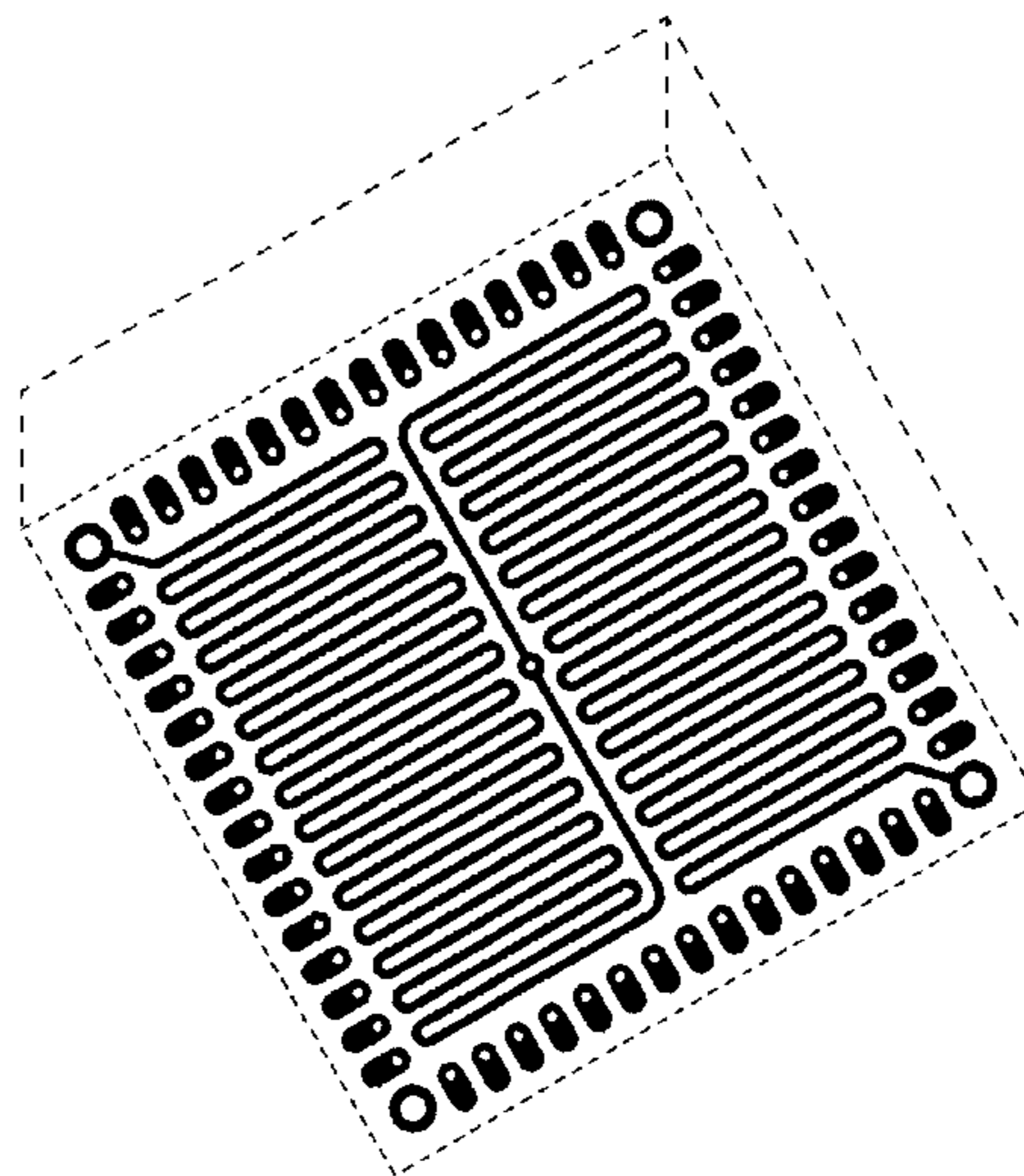
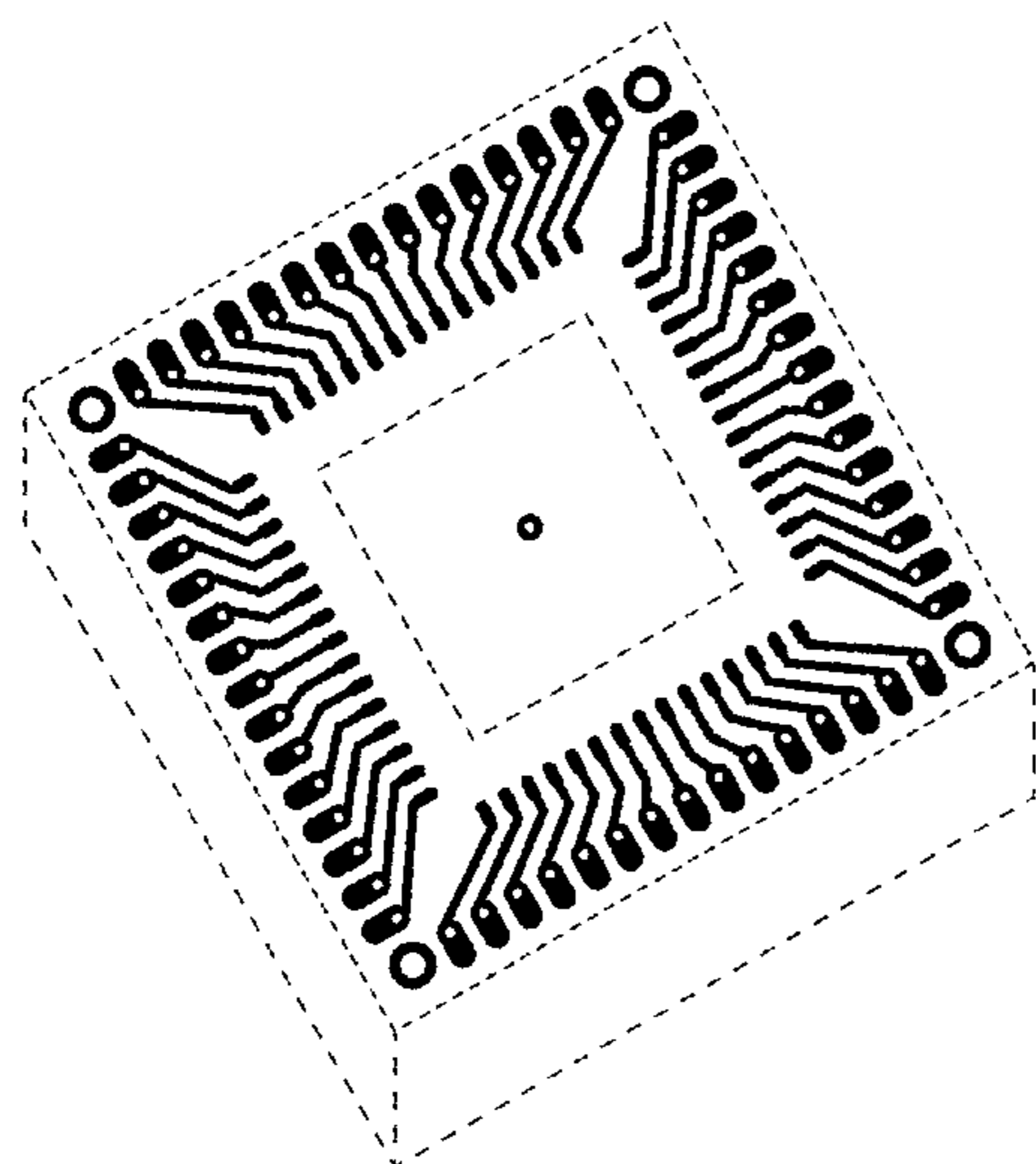
(57) **CLAIM**

The ornamental design for a modular circuit board, as shown and described.

**DESCRIPTION**

FIG. 1 is a top perspective view of a modular circuit board, showing my new design;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a top view thereof;  
FIG. 4 is a bottom view thereof; and,  
FIG. 5 is a side view thereof, all other side views being a mirror image thereof.  
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



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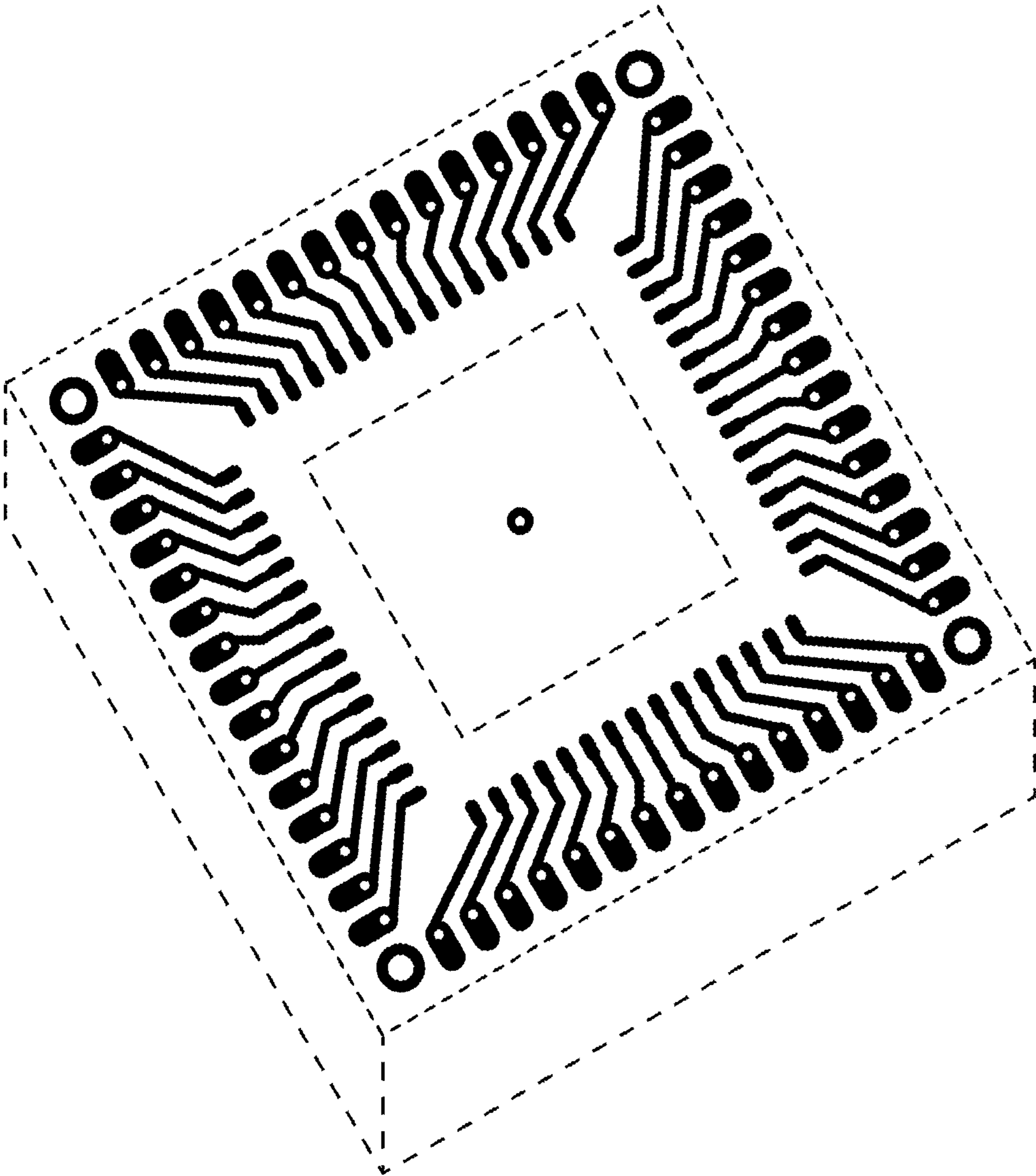


FIG. 1

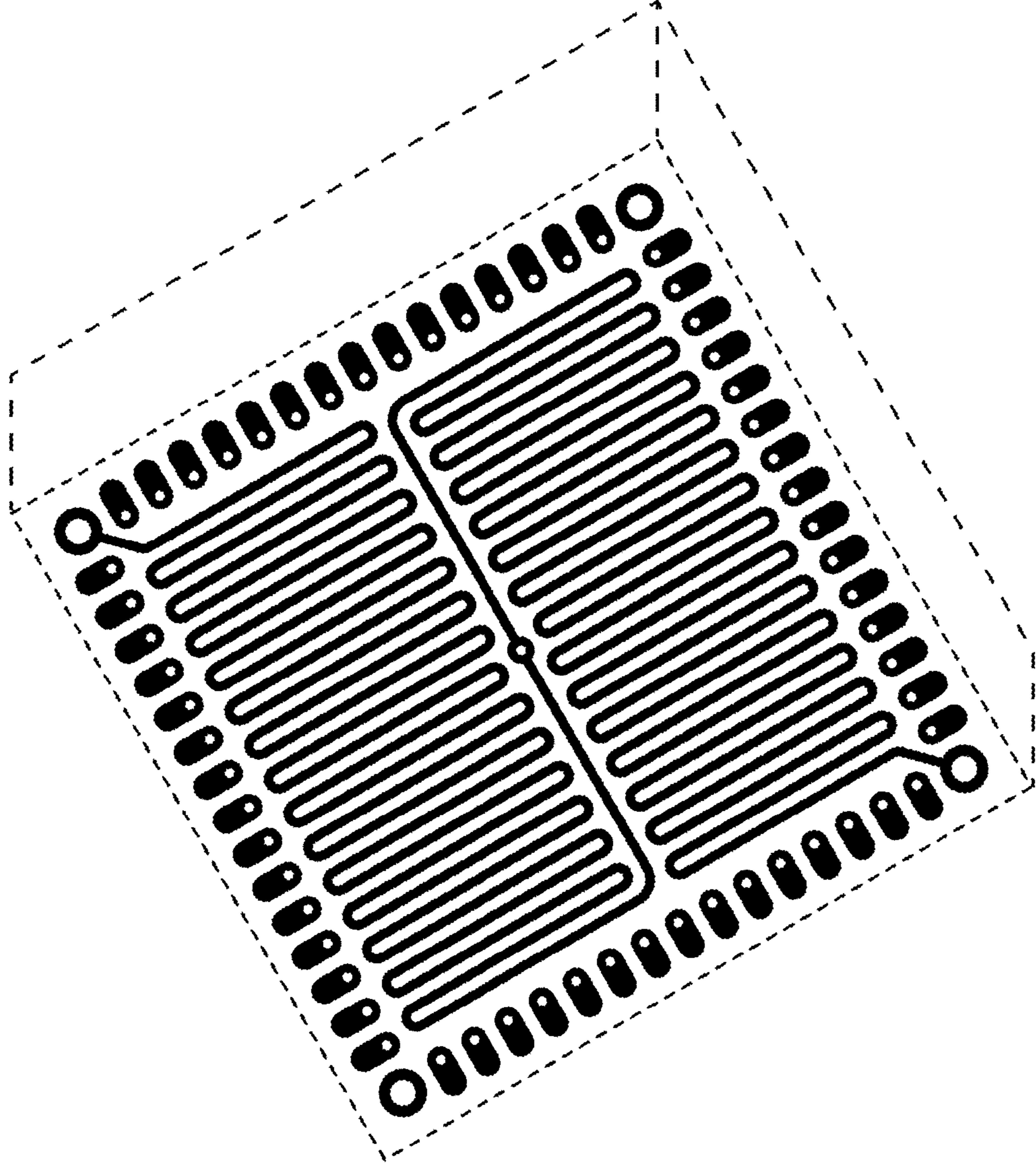


FIG. 2

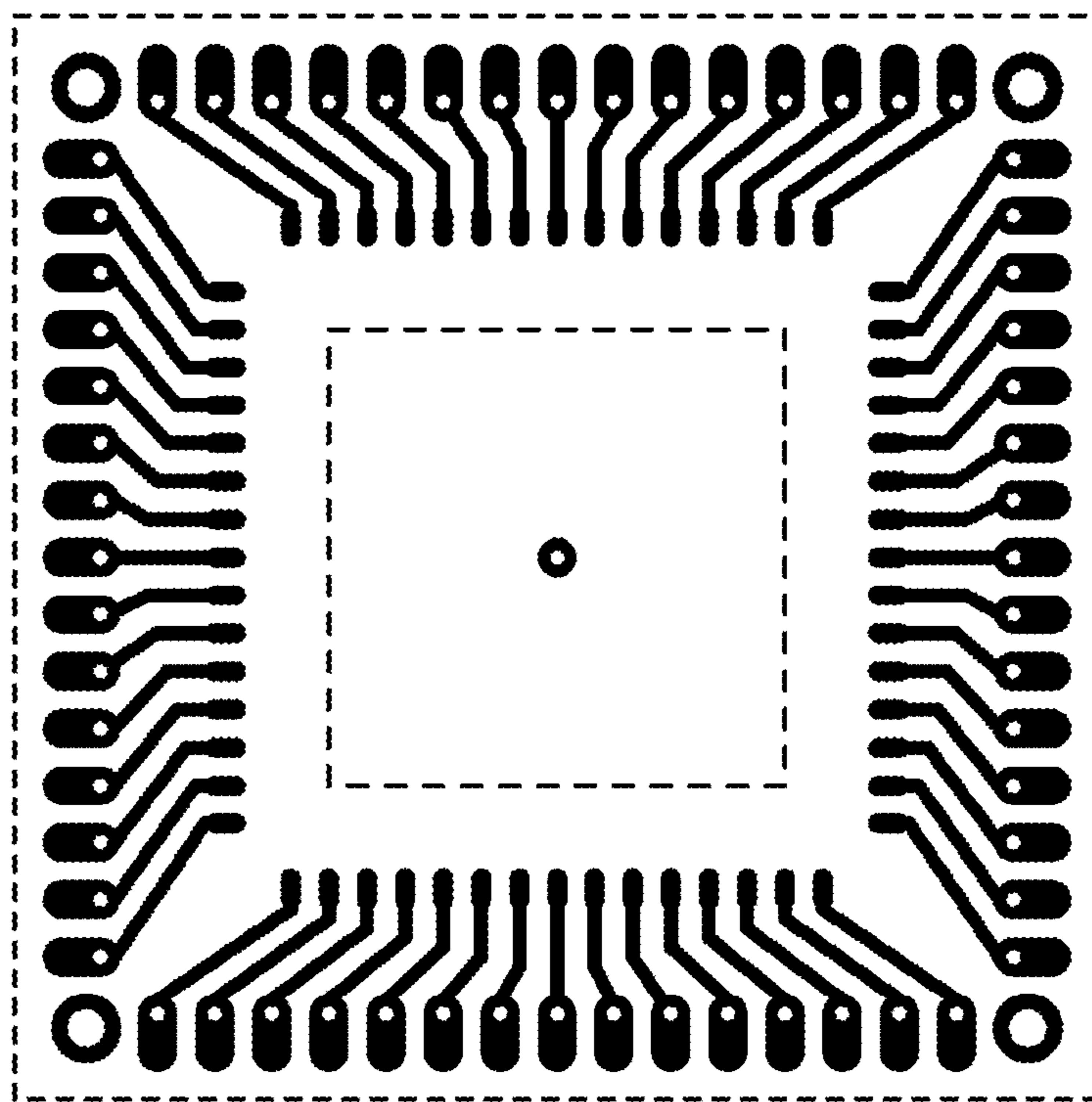


FIG. 3

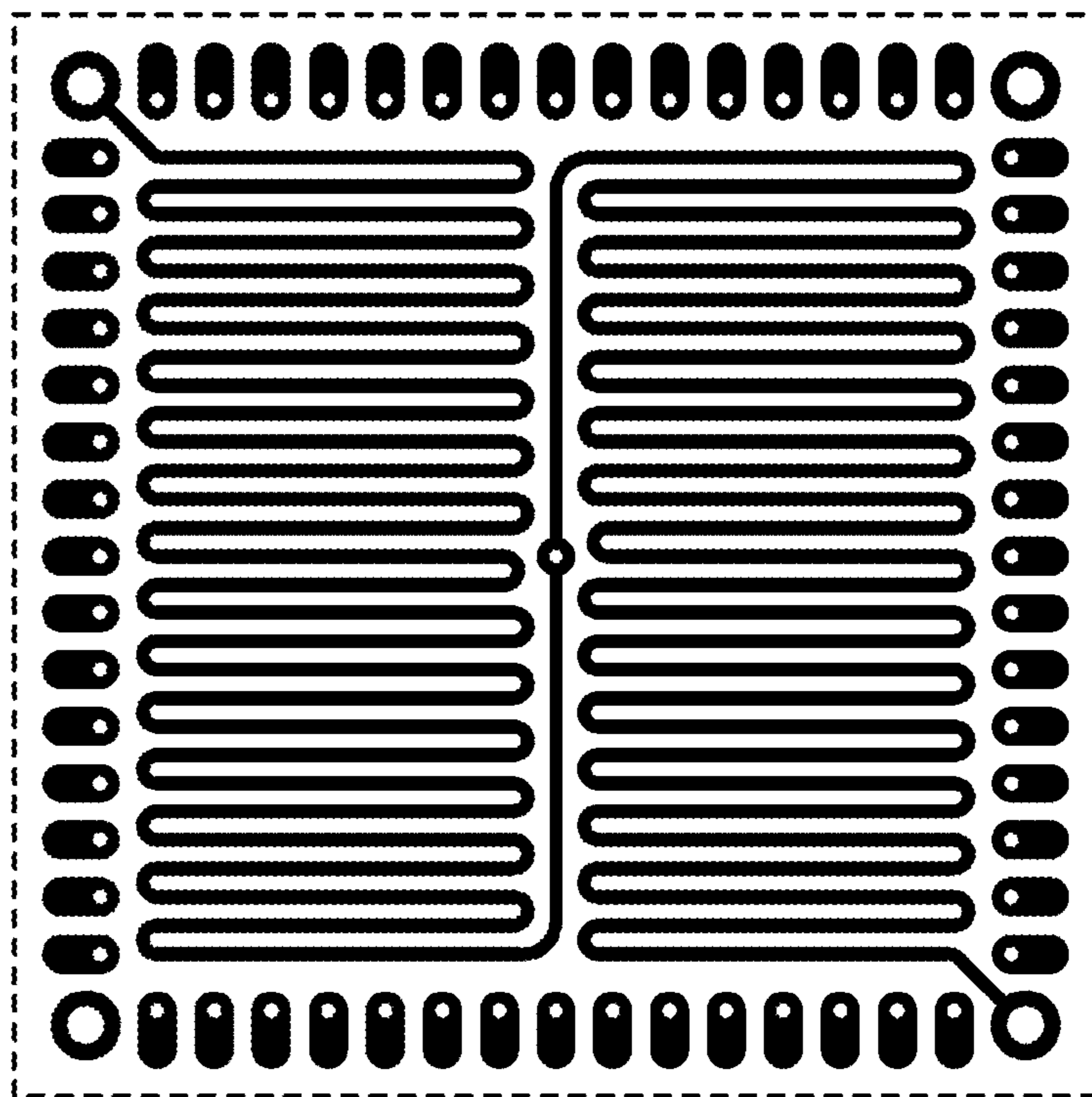


FIG. 4



FIG. 5